

# Laser integrated bonding for OBB XBC module manufacturing

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**Changes  
in the Industry**



**Laser  
Integrated  
Bonding**

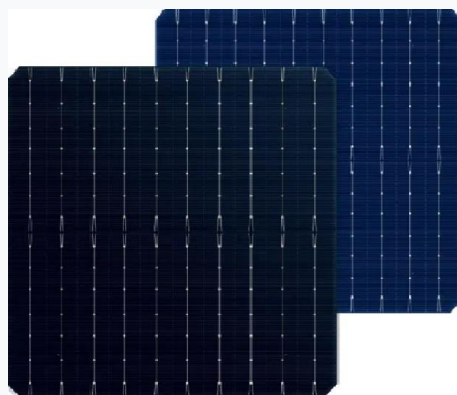


# Solar Cell Development Trend

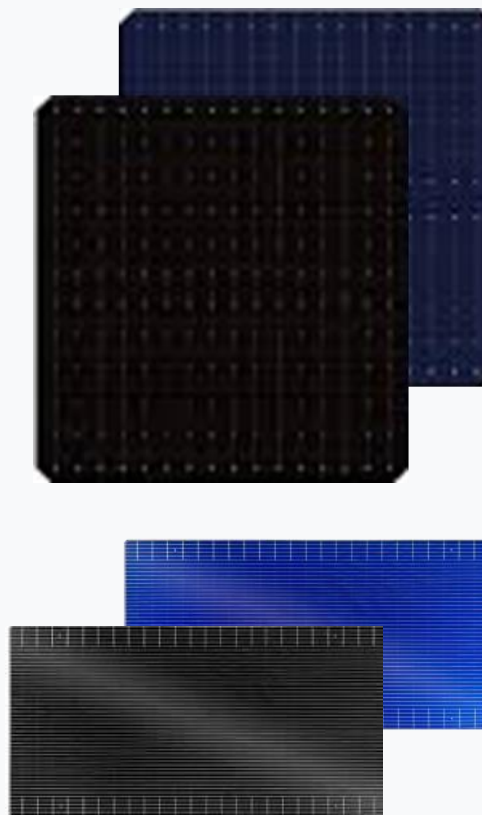
*Sweeping Changes  
within a Decade*



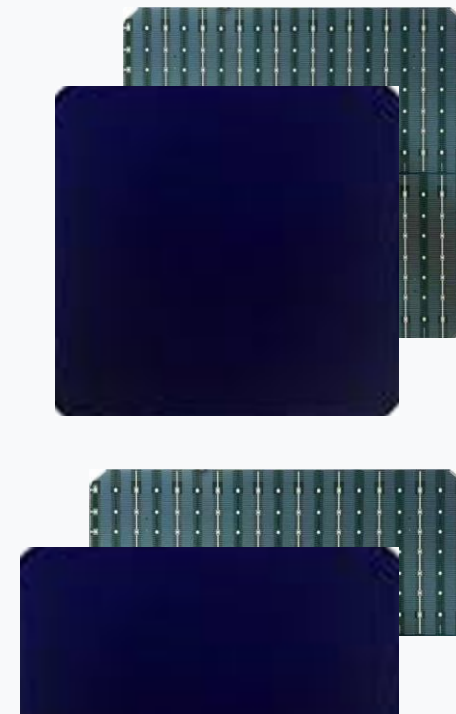
**Before 2016**  
M0 ~ M3  
p-multi-Si  
Al BSF  
2 ~ 5BB



**2016 ~ 2022**  
M3 ~ G12  
p-multi-Si → p-mono-Si  
PERC  
9 ~ 12BB

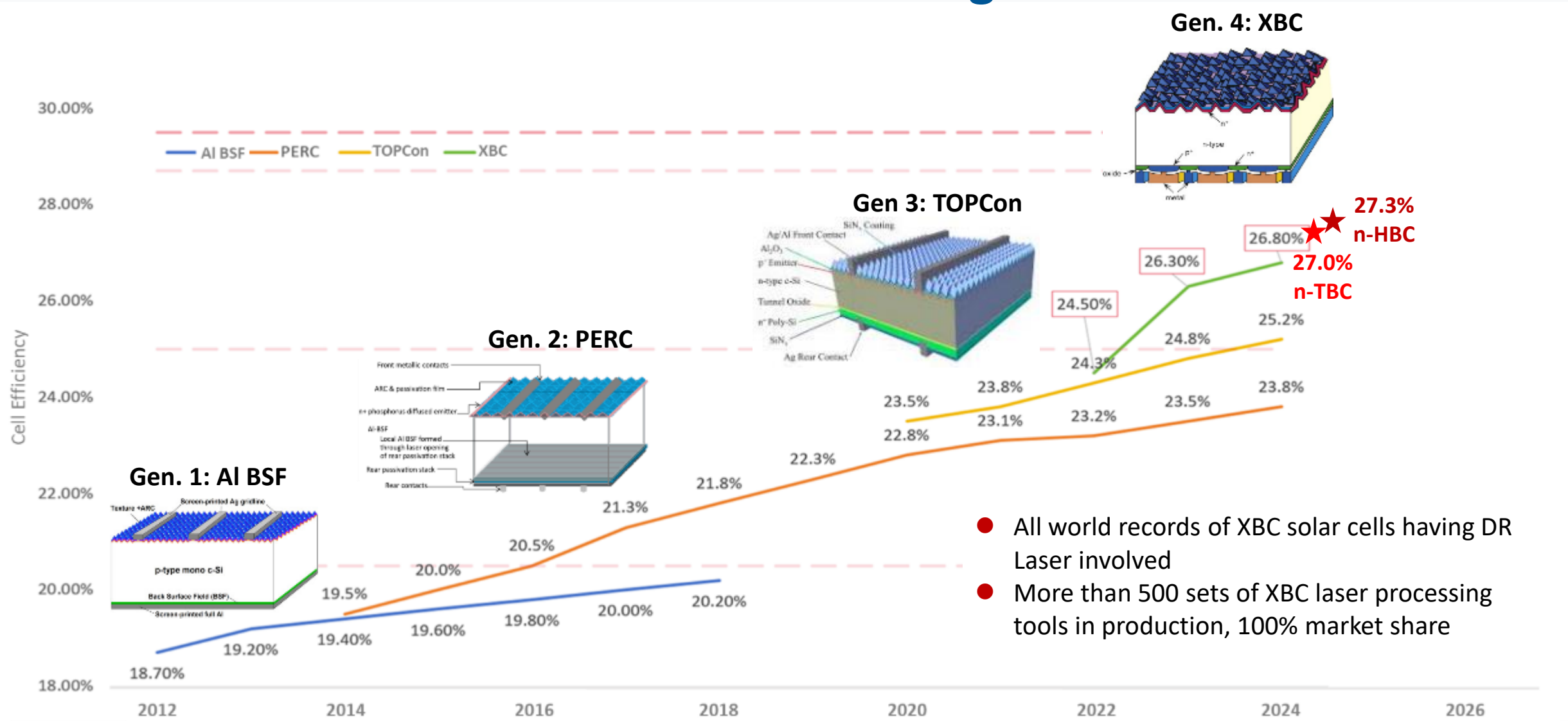


**2022 and beyond**  
M10h ~ G12h, 18XL ~ 19XL  
n-mono-Si  
HJT, TOPCon  
≥16BB, 0BB



**2024 and beyond**  
M10, M10L, M10Lh, G12, G12h  
n-mono-Si  
XBC  
0BB

# The New Generation of Solar Cell Is Coming



- All world records of XBC solar cells having DR Laser involved
- More than 500 sets of XBC laser processing tools in production, 100% market share

# Challenges to OBB XBC Module Manufacturing

## Challenges to PV Modules brought by OBB XBC Solar Cells

### Reliability

- Performance of peel strength
- Performance of TC/TS tests

### Module Power

- CTM ratio
- Yield caused by pseudo soldering, micro-cracks etc.

### Manufacturing Cost

- Consumption of Ag paste on solder pads
- Cost from non-cell materials

### Bifaciality

- Balanced between robust adhesion and wide ribbons or larger solder pads



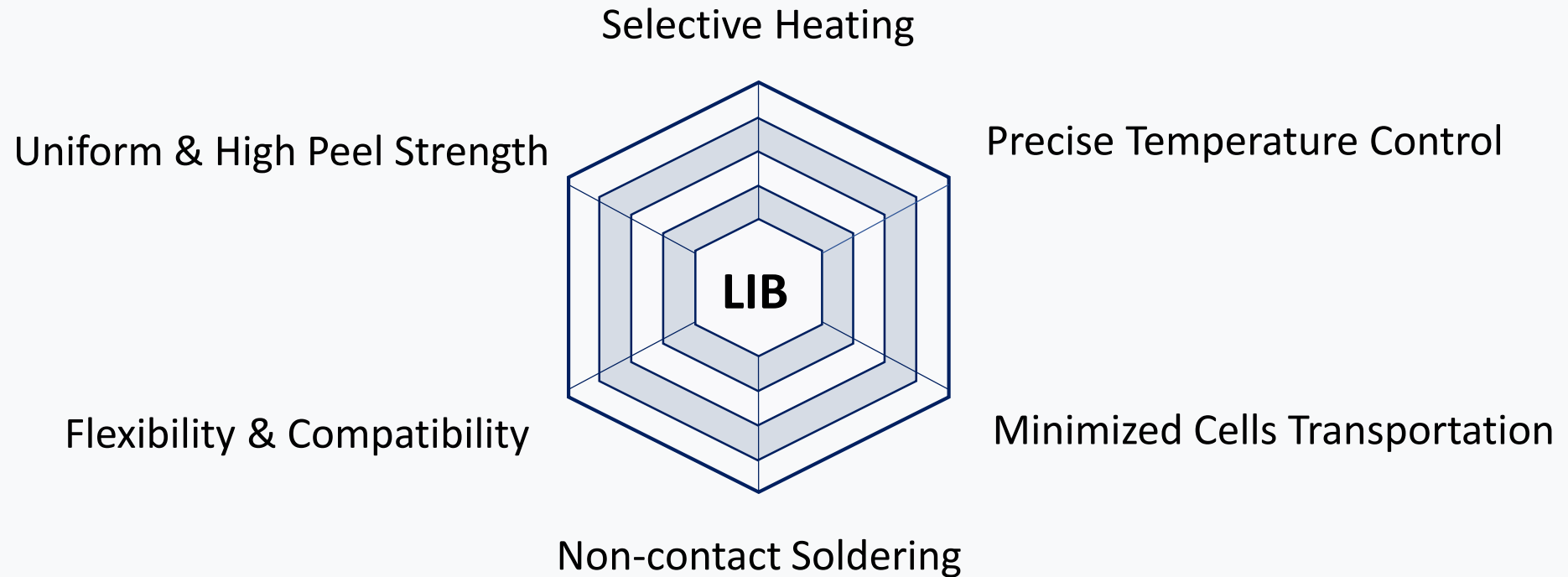
Laser  
Integrated  
Bonding

What is LIB



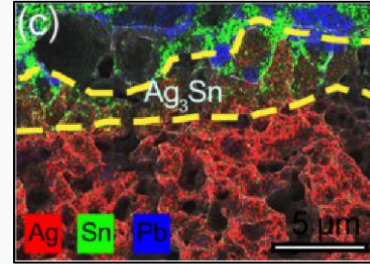
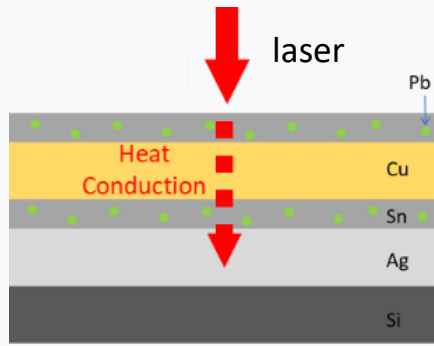
# What is Laser Integrated Bonding

- Laser integrated bonding (LIB) technology is an innovative laser soldering process specially developed for OBB XBC PV modules. The perfect bonding between solar cells and ribbons are formed by the single laser process as a module scale.





# Mechanism of Laser Soldering



Source: J. Zhang et al., Journal of Materials Science: Materials in Electronics, 2019

Selective heating by laser scanning

02

Tin is melted. The compound of Sn and Ag starts to format

04

Absorption

Conduction

Dissolving

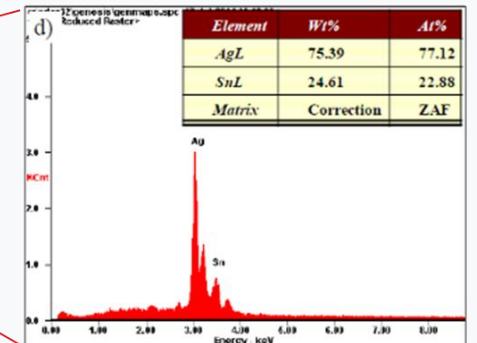
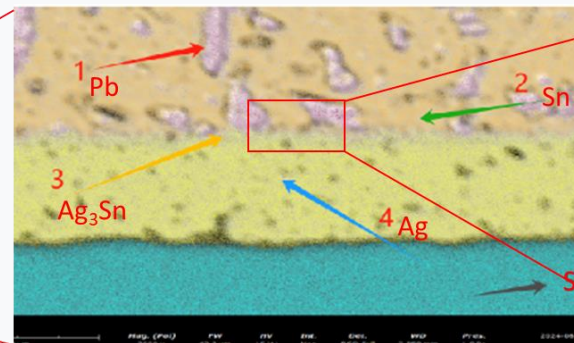
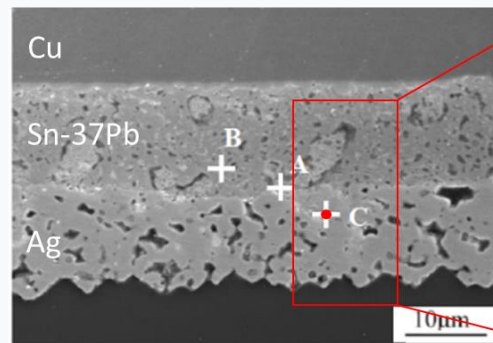
Cooling

01

Heat is conducted through ribbon deeply into soldering pads

03

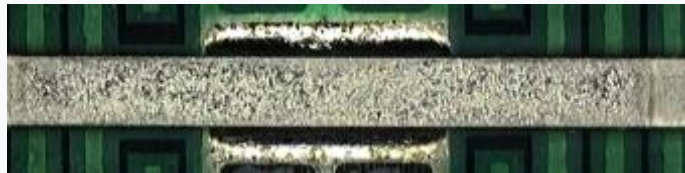
Stable intermetallic compound is formatted after cooling



Source: P. Fang, "Study on Soldering Process and Reliability of Interconnections between Photovoltaic Ribbon and Crystalline Silicon Solar Cell", Harbin Institute of Technology, 2015

# Microstructure of Laser Soldering

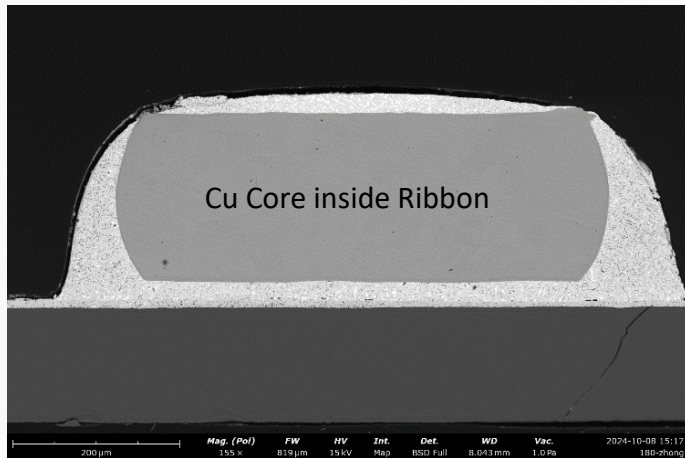
- Cu core inside ribbon is completely wrapped by Sn after laser soldering. Sn also flows along finger, and can ensure robust the quality of laser soldering.
- The morphology of soldered pad after tearing ribbon shows micro dimples. It indicates ductile fracture is happened during tearing, and can tell the robust quality of soldering is done by laser.



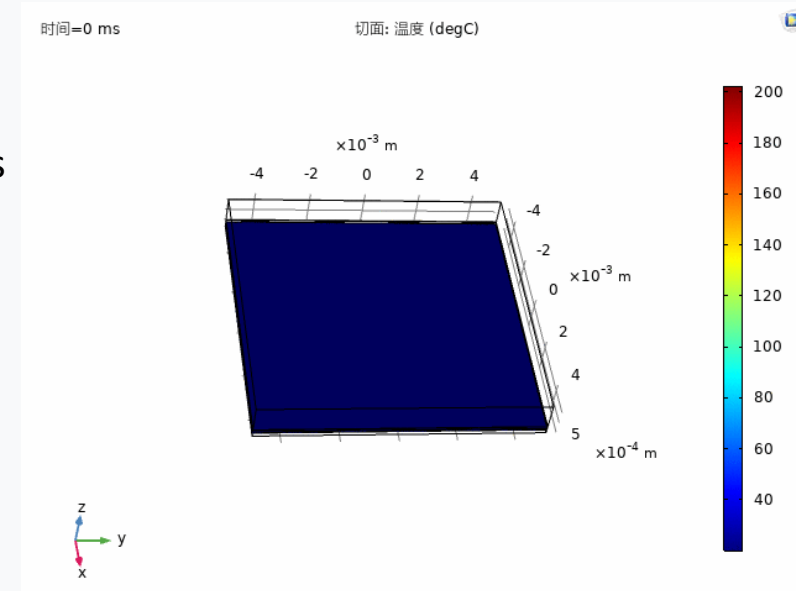
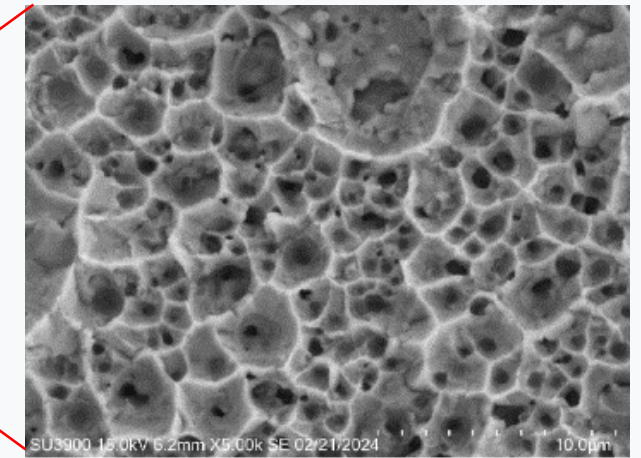
Ribbon Soldered on Solder Pad



Solder Pads after Ribbons torn



X-Section of Soldered Ribbon on Solar Cell





# Solid IP Portfolio

76

In process

40

Authorized

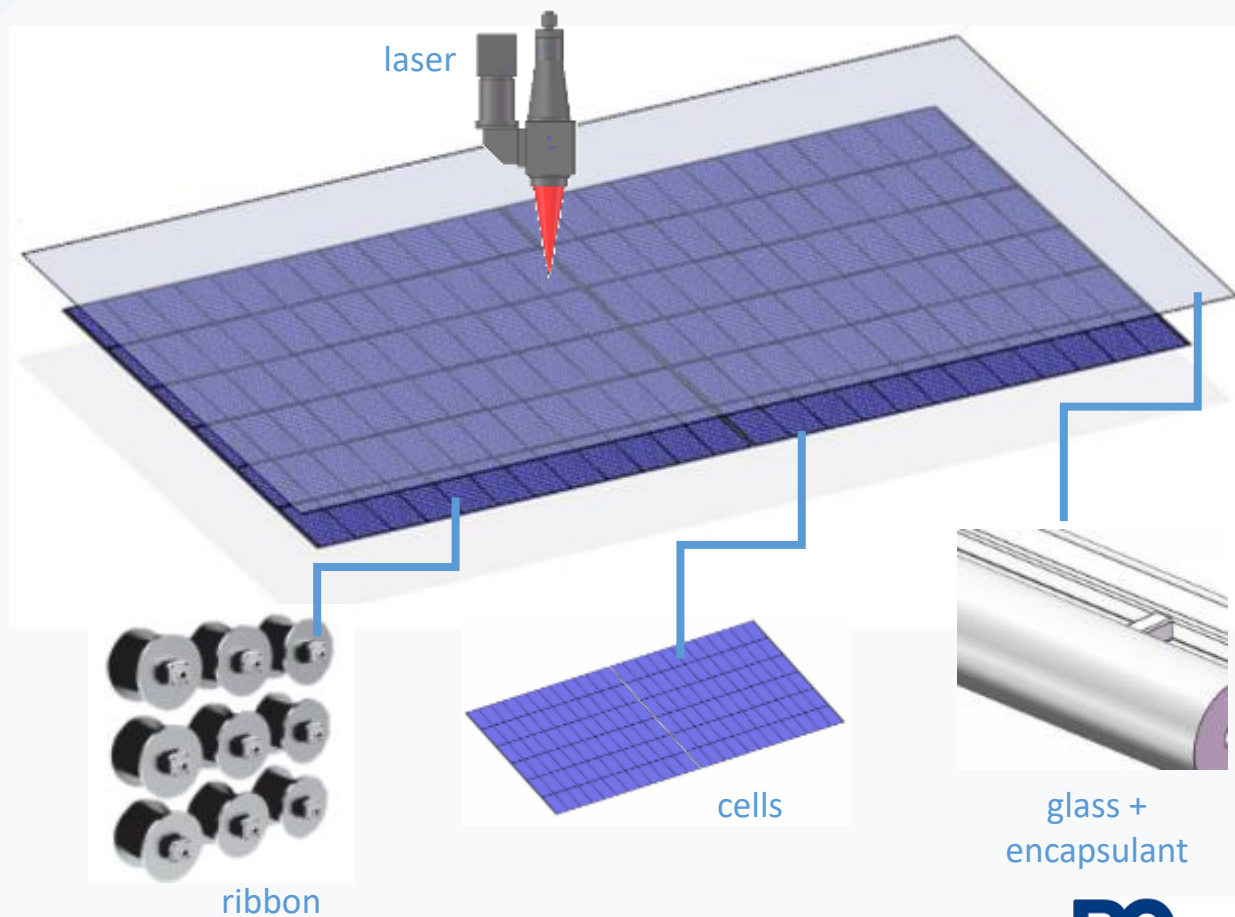
28

Invention  
Patents

7

Authorized  
Invention

EP2993708B1  
JP6410801B2  
US9559248B2  
CN104183666B  
CN111531274B  
.....





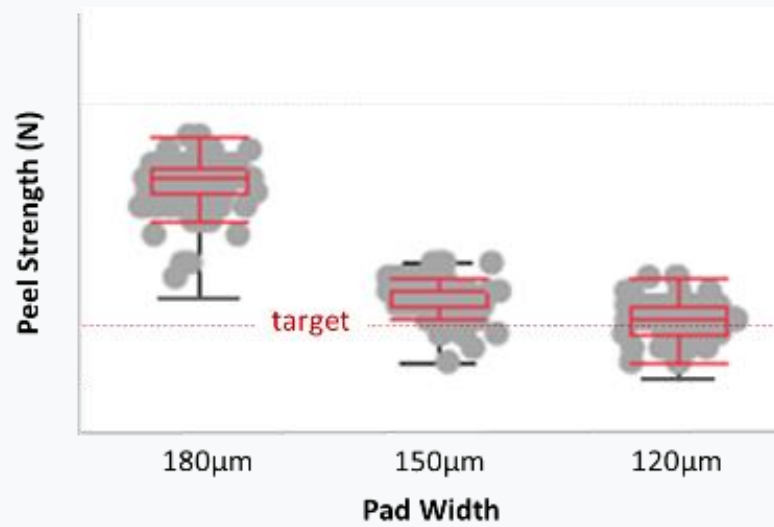
**Laser  
Integrated  
Bonding**

**Critical Factors of  
0BB XBC Module  
Manufacturing**

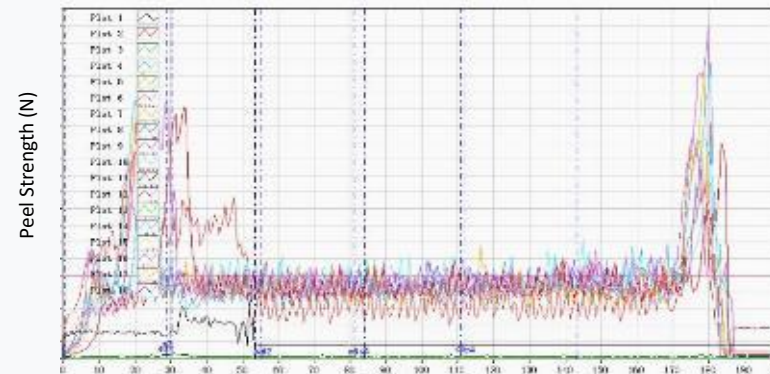


# Reliability – Peel Strength

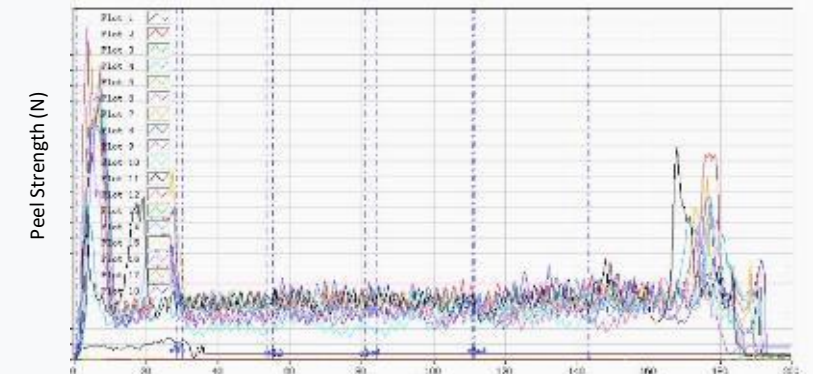
- Peel strength mostly could meet the requirement of OBB XBC modules. However, the proper width of solder pad still needs to be optimized.
- No significant difference of peel strength before and after lamination on positive electrodes and negative electrodes. It proves the robust interface between ribbons and solar cells is formatted by LIB.



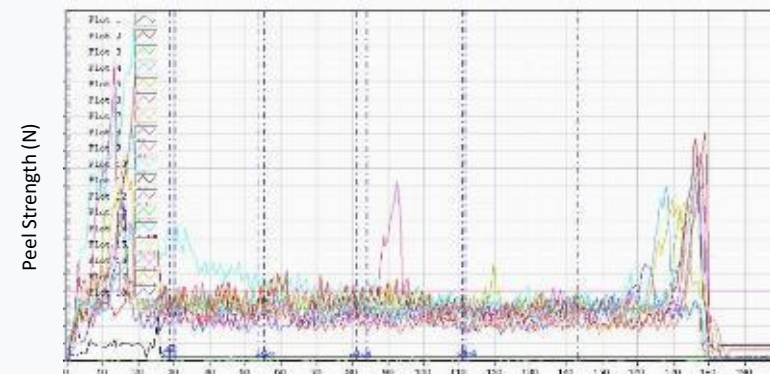
Positive Electrode (before lamination)



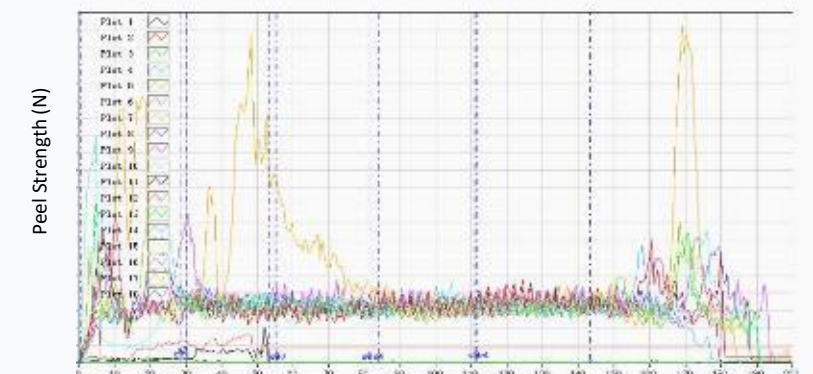
Positive Electrode (after lamination)



Negative Electrode (before lamination)

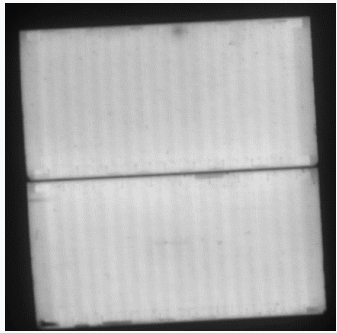
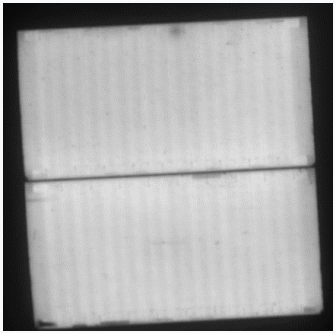
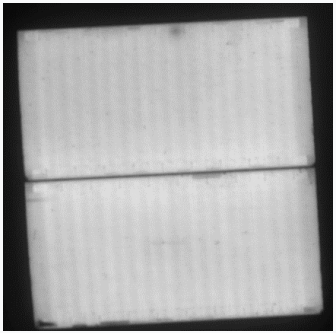
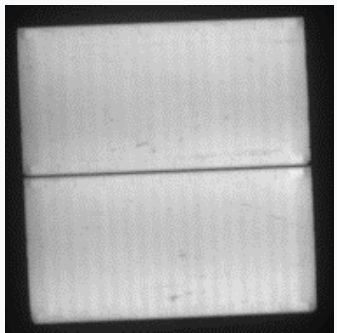
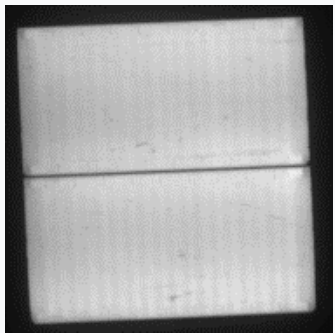
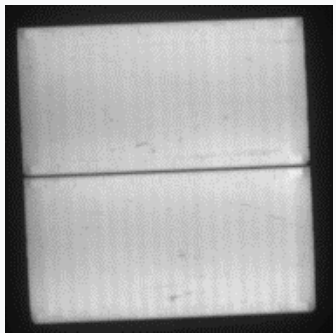


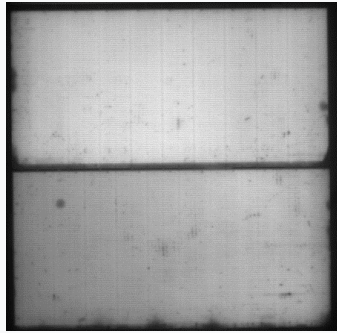
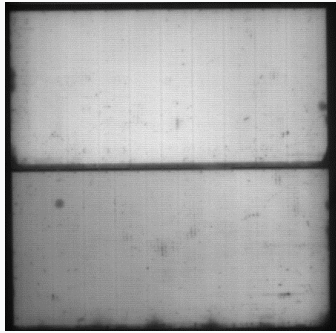
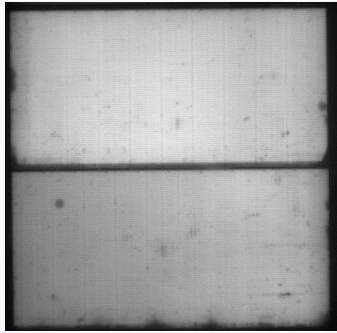
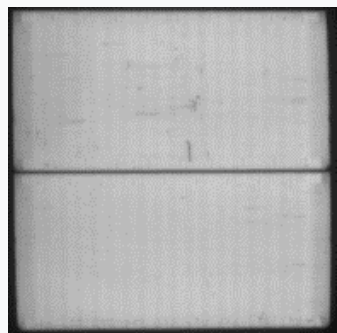
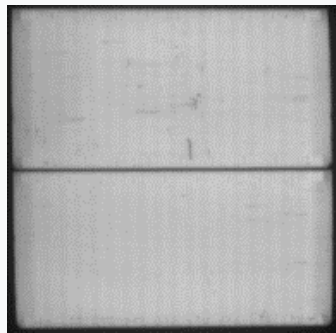
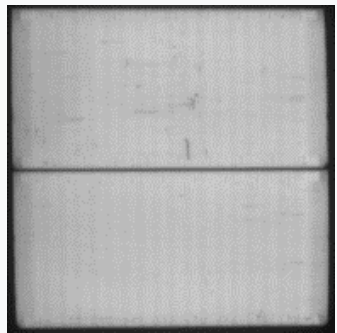
Negative Electrode (after lamination)



# Reliability – PCT & TS Tests

- No significant difference found after PCT 72hrs and PCT 120hrs tests, and after TS200 and TS400 tests.
- Further tests on the varied modules are ongoing by customers.

|          | Initial State  | 72hrs  | 120hrs  |
|----------|--|--|---|
| Sample 1 |   |   |   |
| Sample 2 |  |  |  |

|          | Initial State  | TS200  | TS400  |
|----------|--|--|--|
| Sample 1 |   |   |   |
| Sample 2 |  |  |  |

# CTM Ratio

- Under the same cell efficiency, 0BB XBC modules with LIB inside perform superiorly than references by
  - $\Delta\text{CTM ratio} : > 0.5\%$
  - $\Delta P_{\text{mpp}} : > 4W_p$

|           | $\Delta\text{CTM Ratio}$ | $\Delta\text{FF}$ | $\Delta P_{\text{mpp}}$ |
|-----------|--------------------------|-------------------|-------------------------|
| LIB       | 0.70%                    | 0.41%             | 4.6W                    |
| reference | —                        | —                 | —                       |



# Bifaciality

- Thank to the narrow ribbon! Bifaciality can increase more than 10% than reference. Further fine ribbons and wires are under evaluation. Higher bifaciality can expected soon.

|                                     | Ribbon Spec. | Bifaciality | On-going Evaluation  |
|-------------------------------------|--------------|-------------|--|
| <b>DR Laser<br/>(LIB)</b>           | 0.9mm*0.12mm | 75±5%       | <input checked="" type="checkbox"/> Soldering Pad 0.6mm*0.08mm<br><input checked="" type="checkbox"/> Fine Ribbon 0.6mm*0.25mm<br><input checked="" type="checkbox"/> Wire 0.25mm*0.25mm |
| <b>Reference<br/>(IR Soldering)</b> | 2.5mm*0.15mm | 65±5%       |  |

# Module Cost – Paste Consumption

- The consumption of Ag paste can be reduced more than 20% by converting to OBB design at all customers' sites. The related verifications were done, and pilot production is on going.

|            | Cell Size   | Ribbon # | Ag Paste Consumption (MBB) | Ag Paste Consumption (OBB) | Status Quo   |
|------------|-------------|----------|----------------------------|----------------------------|--|
| Customer A | 182mm*184mm | 20       | reference                  | -23%                       | <input checked="" type="checkbox"/> Peel strength verified<br><input checked="" type="checkbox"/> CTM ratio verified<br><input checked="" type="checkbox"/> TC200, TC400 verified<br><input checked="" type="checkbox"/> Pilot production verified |
| Customer B | 182mm*182mm | 20       | reference                  | -24%                       | <input checked="" type="checkbox"/> Peel strength verified<br><input checked="" type="checkbox"/> CTM ratio verified<br><input checked="" type="checkbox"/> TC200, TC400 verified<br><input checked="" type="checkbox"/> Pilot production verified |
| Customer C | 182mm*192mm | 18       | reference                  | -23%                       | <input checked="" type="checkbox"/> Peel strength verified<br><input checked="" type="checkbox"/> CTM ratio verified<br><input checked="" type="checkbox"/> TC200, TC400 verified<br><input checked="" type="checkbox"/> Pilot production verified |

# Takeaways

- LIB technology can simplify module manufacturing sequence. By one-step laser process on the whole module, the transportation of solar cells can be minimized. The potential risk causing scratches, cracks, chippings can be largely reduced.
- Robust IMC micro-structure is verified by applying LIB technology. LIB technology is suitable for OBB XBC design for the further reduction of Ag consumption to 80 ~ 90mg, and the enhancement of bifaciality of XBC module to 75%, potentially to 80% or above.
- Selective thermal treatment with low and uniform process temperature can avoid high warpage from regular IR soldering. Micro-crack after lamination can be also avoided.
- OBB XBC module with LIB inside had passed TC and TS tests. The reliability of OBB XBC module is recognized. Pilot production by LIB is ongoing.



Laser  
Integrated  
Bonding

DR Laser



# Who We Are

DR Laser (300776. SZ) is a high-tech enterprise committed to developing and supplying advanced laser processing equipment for photovoltaics, semiconductor package, and next-gen. display industries. Founded in 2008, it is based in Wuhan, the geographic center of China, and it currently has another manufacturing base in Wuxi and global R&D centers in Israel and Singapore.



HQs in Wuhan, China



2<sup>nd</sup> Base in Wuxi, China



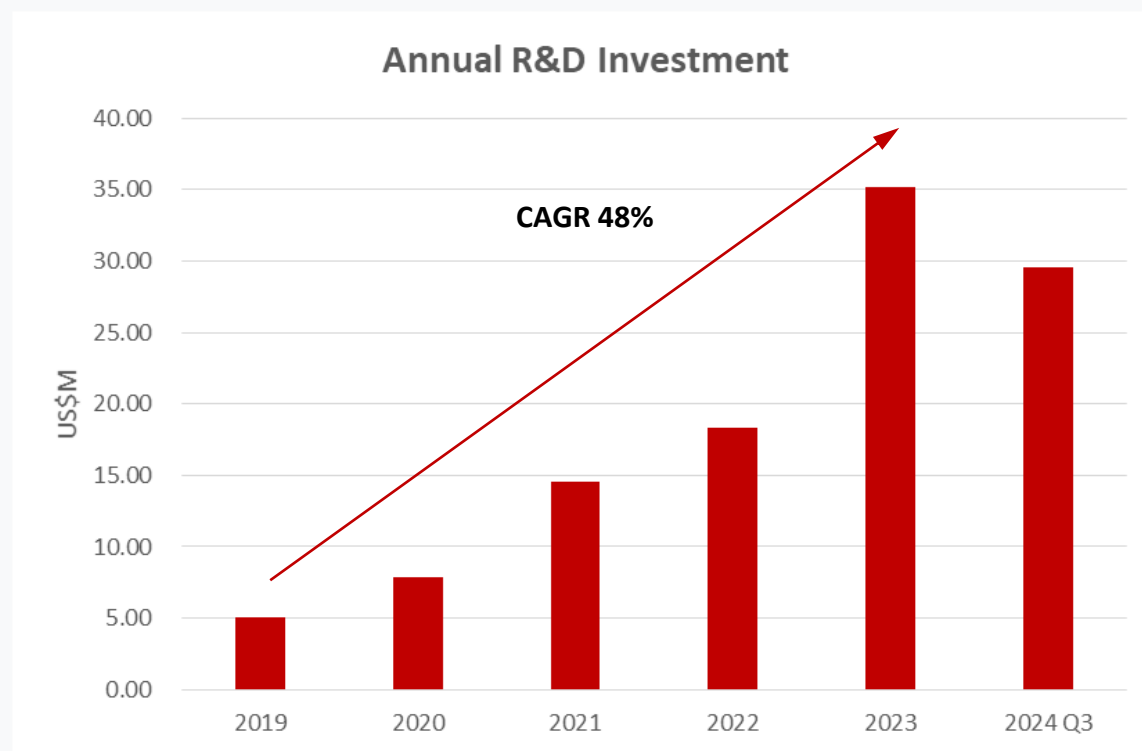
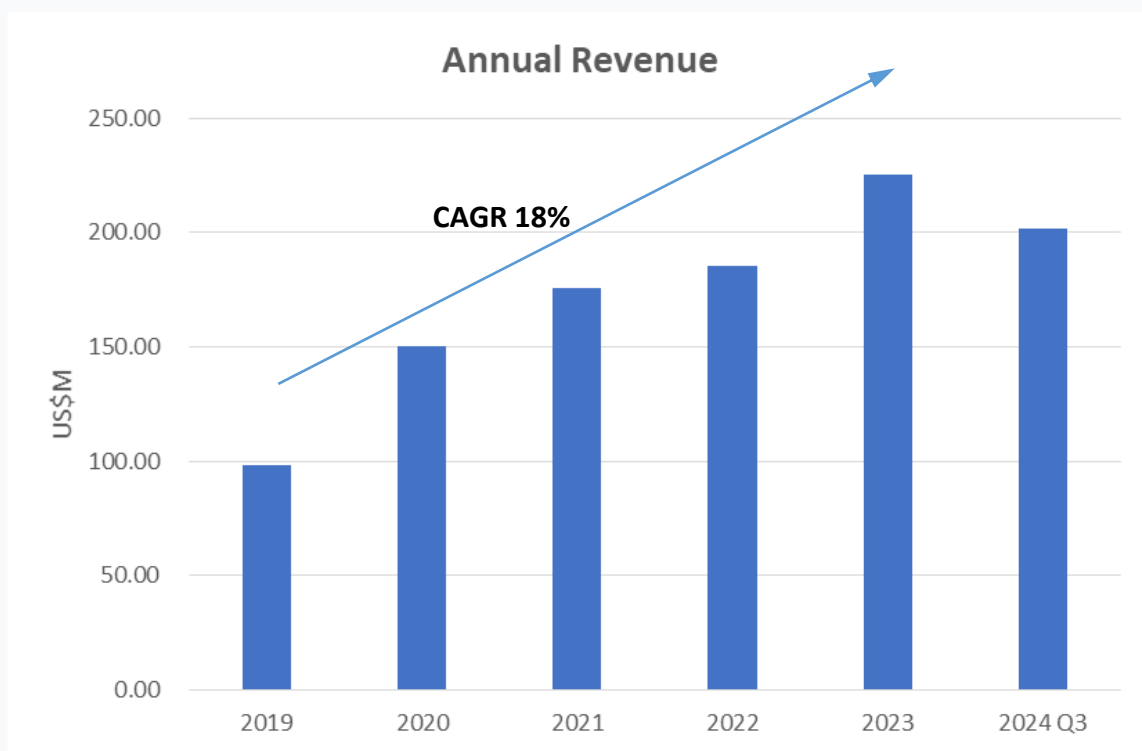
R&D Center in Israel  
(Pattern Transfer Printing)



R&D Center in Singapore  
(Advanced Semiconductor Package, Micro LED)

# What We Do

- Double digits of CAGR in the past 5 years. Targeting to break US\$250M revenue in 2024.
- Close to 50% of GAGR in the past 5 years on annual R&D investment. Further investing is ongoing without stop.



# What We Offer

- Complete product family covering all c-Si solar cell technologies



PERC LCO



PERC LDSE



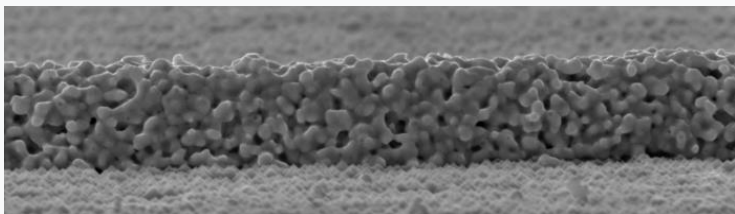
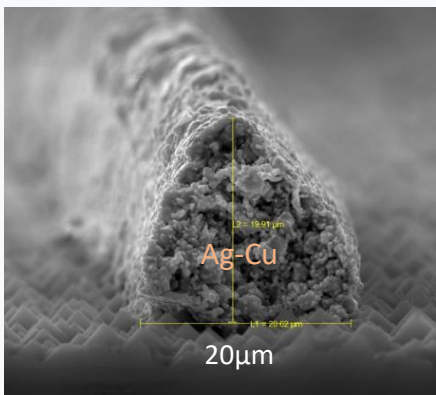
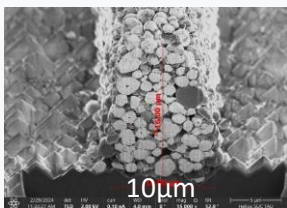
TOPCon TCSE



TOPCon LIF



XBC Laser Patterning



State-of-the-art Metallization Line for TOPCon and HJT including Pattern Transfer Printing

# Whom We Serve



More than 7,000 sets of laser processing tools shipping out







**THANKS**